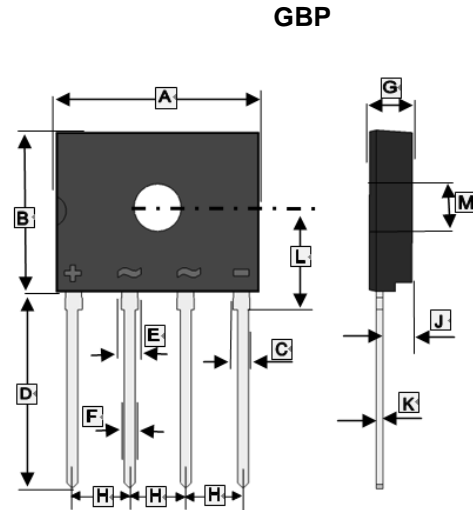


RoHS Compliant Product

FEATURES

- Ideal for printed circuit board
- Low forward voltage drop, high current capability
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- These are Halogen & Pb Free components
- This series is UL recognized under Component Index, file number E255340



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	13.6	14.0	G	2.9	3.3
B	10.6	11	H	3.5	4.1
C	1	1.5	J	1.8	2.4
D	12.6	13.8	K	0.4	0.6
E	1.05	1.25	L	6.7	7.3
F	0.65	0.85	M	φ 3.0	φ 3.4

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, de-rate current by 20%.)

Parameter	Symbol	Part Number				Unit
		S8GBP20-C	S8GBP40-C	S8GBP60-C	S8GBP80-C	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	V
Average Rectified Output Current @60HZ sine wave, R-load	$T_C=126^\circ\text{C}$ (with heat sink)	8				A
	$T_A=25^\circ\text{C}$ (without heat sink)	1.4				
Peak Forward Surge Current @ 60Hz sine wave, 1 cycle, $T_J=25^\circ\text{C}$	I_{FSM}	165				A
Maximum Peak Forward Voltage ³	V_{FM}	1				V
Peak Reverse Current ²	I_{RRM}	10				μA
I^2t Rating for Fusing @3ms≤t<8.3ms, $T_J=25^\circ\text{C}$, Rating of per diode	I^2t	113				A ² s
Mounting Torque @ Recommend torque:5kg·cm	TOR	8				Kg·cm
Dielectric Strength ¹	Vdis	2				kV
Typical Thermal Resistance (with heat sink)	$R_{\theta JC}$	1.5				°C/W
Typical Thermal Resistance(without heat sink)	$R_{\theta JA}$	55				°C/W
Typical Thermal Resistance(without heat sink)	$R_{\theta JL}$	15				°C/W
Operating and Storage temperature range	T_J, T_{STG}	150, -55~150				°C

Notes :

1. Terminals to case · AC 1 minute
2. $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode.
3. $I_{FM}=4.0A$, Pulse measurement, Rating of per diode

RATINGS AND CHARACTERISTIC CURVES

